

Magnesium Oxide MgO

Sputtering Targets



Kurt J. Lesker[®]
Company

MATERIALS[™]
DIVISION

Applications

- Non-volatile Memory or Ferroelectric RAM
- Thin film capacitors

Features

- High purity
- Custom Sizes Available

Process

- Manufacturing
 - Cold pressed
 - Sintered
 - Indium bonded to backing plate
- Cleaning and final packaging
 - Cleaned for use in vacuum
 - Protection from environmental contaminants
 - Protection during shipment

Options

- 99.95% minimum purity
- Up to 12.0" Diameter Targets Available
- Planar Tiles Up to 8" X 5" for Larger Target Configurations

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Specifications

Typical Analysis - 99.95% (3N5) Purity

Metallic Impurities, ppm by weight

Ag	Al	As	B	Bi	Ca	Co	Cr	Fe	K	Mn
<5	<20	<5	<50	<5	<50	<5	<5	<50	<50	<5

Mo	Na	Ni	Pb	Sb	Sn	Sr	Ti	V	Zn	Zr
<5	<20	<5	<20	<10	<10	<50	<5	<5	<5	<5

Theoretical Density	3.58 g/cc
Typical Density	>3.1 g/cc
Sputter	RF, RF-R
Max Power Density (Watts/Square Inch)	20
Melting Point	2,852°C
Appearance	White/Yellow/Beige
Z Ratio	0.411
Particle Size	D50

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